



DAC/TFW

**PATENT**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

U.S. Patent No. 6,756,665  
Issued: June 29, 2004

Serial No. 10/635,564  
Filed: August 7, 2003

For: **INTEGRATED CIRCUIT PACKAGE STRUCTURE WITH HEAT DISSIPATING DESIGN**

**PETITION FOR DUPLICATE LETTERS PATENT  
UNDER 37 C.F.R. 1.182**

**MAIL STOP PETITION**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA. 22313-1450

Sir:

The undersigned respectfully petitions for issuance of a duplicate letters patent for the above-identified patent. A Declaration is included which states that a diligent search was made for the original Letters Patent No. 6,756,665.

The petition fee (37 CFR 1.182; 37 CFR 1.17(h)) of \$400 is enclosed.

The granting of the petition is respectfully requested.

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Respectfully submitted,

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Registration No. 31,725

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Date: July 14, 2006

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## VERIFIED DECLARATION

I, Steven Hung the manager of VIA Technologies, Inc. now declare and confirm that the original Grant (Letter Patent) of U.S. Patent No. 6,756,665B1 which I have received was lost even with a diligent search. Therefore, I apply again for the original Grant.

I hereby declare that all statements made herein of my own knowledge are true and all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like to make are punishable by fine or imprisonment, or both, under section 1001 of title 18 of the United State Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Steven Hung  
Signature

2006/7/5

Date